

11/09/01  
JC978 U.S. PRO

01-08-02

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Docket No.: 5545 (2616-012)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Box Patent Application  
Commissioner for Patents  
Washington, D.C. 20231

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10/039333  
11/09/01

Re: Inventors: Gene H. LEE, Nam-Hun KIM  
Title: *Method for Etching Tungsten Using NF<sub>3</sub> and Cl<sub>2</sub>*

Transmitted herewith is the patent application identified above, including:

☒ Specification, claims and abstract, totaling 20 pages.

☒ Drawings totaling 4 pages, \_\_\_ Formal ☒ Informal.

☒ Executed Declaration and Power of Attorney.

☒ Assignment of the invention to **Applied Materials, Inc.**

☒ Assignment Recordation Cover Sheet

☒ Information Disclosure Statement (37 C.F.R. § 1.98)

FEE CALCULATION

Fee Items	Claims Filed	Included With Basic Fee	Extra Claims	Fee Rate	Total
Total Claims	21	-20=	1	X\$18.00	\$ 18.00
Independent Claims	3	-3=	0	X\$84.00	\$ 0.00
Basic Filing Fee				\$740.00	\$740.00
TOTAL FEES					\$758.00

☒ The Commissioner is hereby authorized to charge \$758.00 to Deposit Account No. 50-1074.

☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 50-1074. A duplicate copy of this transmittal is enclosed.

☒ Please address all future correspondence to:

**PATENT COUNSEL  
APPLIED MATERIALS, INC.**  
Legal Affairs Department  
P.O. BOX 450A  
Santa Clara, CA. 95052

I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

Express Mail Receipt No. EL661803784US

Date of Deposit 11-9-01

Signature [Signature]

Respectfully submitted

[Signature]

Robert W. Mulcahy  
Registration No. 25,436